

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4071463

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MASATOSHI OGATA	01/07/2016
NORIO ISHITSUKA	01/07/2016
SHINOBU TASHIRO	01/14/2016
NOBORU TOKUYASU	09/13/2016
TAKESHI MORINO	01/22/2016
RECEIVING PARTY DATA	
Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.
Street Address:	2520 TAKABA
City:	HITACHINAKA-SHI, IBARAKI
State/Country:	JAPAN
Postal Code:	312-8503
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14907118
CORRESPONDENCE DATA	
Fax Number:	(202)672-5399
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-672-5300
Email:	ipdocketing@foley.com
Correspondent Name:	FOLEY & LARDNER LLP
Address Line 1:	3000 K STREET N.W.
Address Line 2:	SUITE 600
Address Line 4:	WASHINGTON, D.C. 20007-5109
ATTORNEY DOCKET NUMBER:	091715-0202
NAME OF SUBMITTER:	P. SHIEK FOR T. G. BILODEAU
SIGNATURE:	/P. SHIEK/
DATE SIGNED:	09/27/2016
Total Attachments: 3	

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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI AUTOMOTIVE SYSTEMS, LTD., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

THERMAL-TYPE AIR FLOW METER

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) OGATA Masatoshi	<u>Ogata Masatoshi</u>	<u>1 / 7 / 2016</u>
2) ISHITSUKA Norio	<u>Ishitsuka Norio</u>	<u>1 / 7 / 2016</u>
3) TASHIRO Shinobu	<u>Shinobu Tashiro</u>	<u>1 / 14 / 2016</u>
4) TOKUYASU Noboru	_____	_____
5) MORINO Takeshi	_____	_____
6) _____	_____	_____
7) _____	_____	_____
8) _____	_____	_____
9) _____	_____	_____
10) _____	_____	_____

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INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) OGATA Masatoshi

2) ISHITSUKA Norio

3) TASHIRO Shinobu

4) TOKUYASU Noboru TOKUYASU Noboru

13 / 9 / 2016

5) MORINO Takeshi

6)

7)

8)

9)

10)

PATENT

REEL: 039869 FRAME: 0939

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1) OGATA Masatoshi _____	_____
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3) TASHIRO Shinobu _____	_____
4) TOKUYASU Noboru _____	_____
5) MORINO Takeshi <u>MORINO Takeshi</u> _____	<u>1/22/2016</u> _____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____